SEMICONDUCTOR PACKAGES AND METHODS OF PACKAGING SEMICONDUCTOR DEVICES

ABSTRACT

Semiconductor packages and methods of forming a semiconductor package are disclosed. The method includes providing at least one die having first and second surfaces. The second surface of the die includes a plurality of conductive pads. A permanent carrier is provided and the at least one die is attached to the permanent carrier. The first surface of the at least one die is facing the permanent carrier. A cap having first and second surfaces is formed to encapsulate the at least one die. The first surface of the cap contacts the permanent carrier and the second surface of the cap is disposed at a different plane than the second surface of the die.

Fig. 1